

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6233xxxx9R-G
Typical Mass: 1.4 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.126	Silicon	90000	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	0.442	Nickel	315700	7440-02-0
		Silver	30000	7440-22-4
		Gold	3600	7440-57-5
Die attach	0.004	Epoxy Resin	2900	—
		Silica	2100	60676-86-0
Bonding wire	0.030	Gold	21600	7440-57-5
Resin	0.521	Silica	372000	60676-86-0
		Epoxy Resin	48100	—
		Phenol Resin	48100	—
		Metal hydroxide	65900	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."